

# 8-Bit Serial-In/Parallel-Out Shift Register

## MM74HC164

### Description

The MM74HC164 utilizes advanced silicon-gate CMOS technology. It has the high noise immunity and low consumption of standard CMOS integrated circuits. It also offers speeds comparable to low power Schottky devices.

This 8-bit shift register has gated serial inputs and CLEAR. Each register bit is a D-type master/slave flip-flop. Inputs A & B permit complete control over the incoming data. A LOW at either or both inputs inhibits entry of new data and resets the first flip-flop to the low level at the next clock pulse. A high level on one input enables the other input which will then determine the state of the first flip-flop. Data at the serial inputs may be changed while the clock is HIGH or LOW, but only information meeting the setup and hold time requirements will be entered. Data is serially shifted in and out of the 8-bit register during the positive going transition of the clock pulse. Clear is independent of the clock and accomplished by a low level at the CLEAR input.

The 74HC logic family is functionally as well as pin-out compatible with the standard 74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to  $V_{CC}$  and ground.

### Features

- Typical Operating Frequency: 50 MHz
- Typical Propagation Delay: 19 ns (clock to Q)
- Wide Operating Supply Voltage Range: 2 V to 6 V
- Low Input Current: 1  $\mu$ A maximum
- Low Quiescent Supply Current: 160  $\mu$ A maximum (74HC Series)
- Fanout of 10 LS-TTL Loads

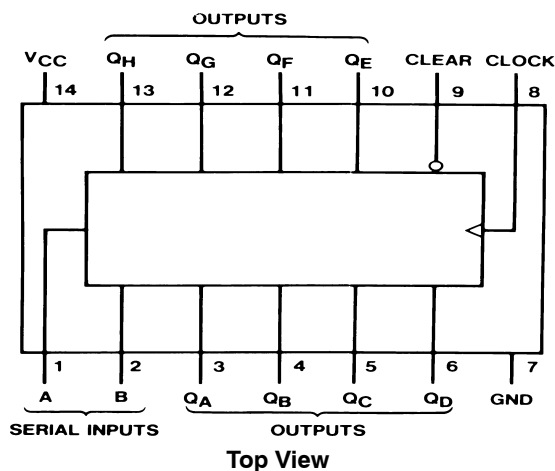
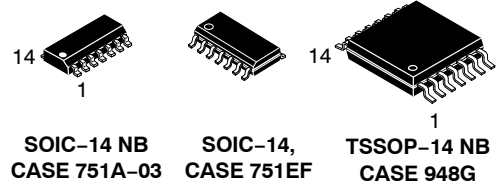
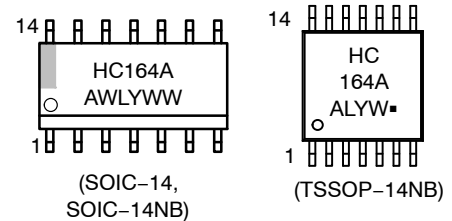


Figure 1. Connection Diagram



### MARKING DIAGRAMS



HC164A = Specific Device Code  
A = Assembly Location  
L/WL = Wafer Lot  
Y/YY = Year  
W/WW = Work Week  
G = Pb-Free Package

### TRUTH TABLE

Inputs				Outputs			
Clear	Clock	A	B	Q <sub>A</sub>	Q <sub>B</sub> ... Q <sub>H</sub>		
L	X	X	X	L	L ... L		
H	L	X	X	Q <sub>AO</sub>	Q <sub>BO</sub> ... Q <sub>HO</sub>		
H	↑	H	H	H	Q <sub>AN</sub> ... Q <sub>GN</sub>		
H	↑	L	X	L	Q <sub>A</sub> ... Q <sub>GN</sub>		
H	↑	X	L	L	Q <sub>AN</sub> ... Q <sub>GN</sub>		

H = HIGH Level (steady state)  
L = LOW Level (steady state)  
X = Irrelevant (any input, including transitions)  
↑ = Transition from LOW-to-HIGH level.

Q<sub>AO</sub>, Q<sub>BO</sub>, Q<sub>HO</sub> = the level of Q<sub>A</sub>, Q<sub>B</sub>, or Q<sub>H</sub>, respectively, before the indicated steady state input conditions were established.

Q<sub>AN</sub>, Q<sub>GN</sub> = The level of Q<sub>A</sub> or Q<sub>G</sub> before the most recent = transition of the clock; indicated a one-bit shift.

### ORDERING INFORMATION

See detailed ordering and shipping information on page 4 of this data sheet.

# MM74HC164

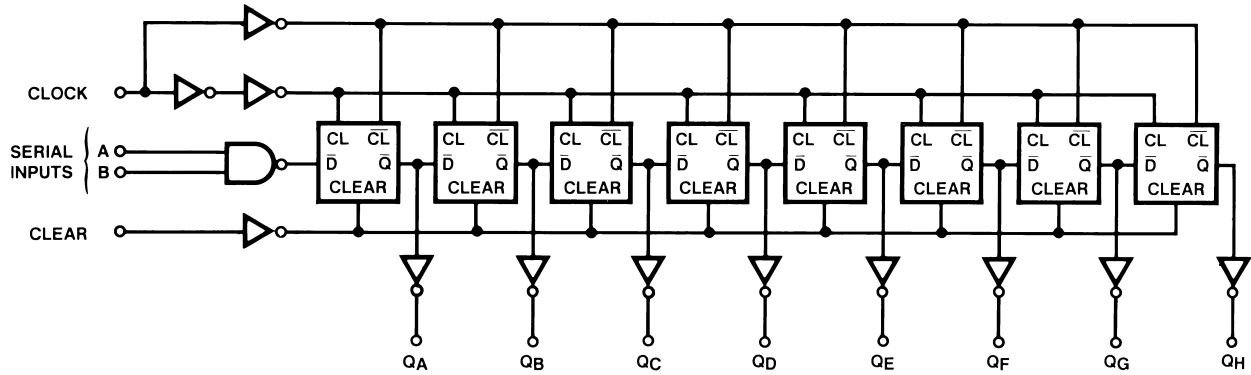


Figure 2. Logic Diagram

## ABSOLUTE MAXIMUM RATINGS (Note 1)

Symbol	Parameter	Rating	Unit
$V_{CC}$	Supply Voltage	-0.5 to +6.5	V
$V_{IN}$	DC Input Voltage	-0.5 to $V_{CC}+0.5$	V
$V_{OUT}$	DC Output Voltage	-0.5 to $V_{CC}+0.5$	V
$I_{IK}, I_{OK}$	Clamp Diode Current	$\pm 20$	mA
$I_{OUT}$	DC Output Current, per pin	$\pm 25$	mA
$I_{CC}$	DC $V_{CC}$ or GND Current, per pin	$\pm 50$	mA
$T_{STG}$	Storage Temperature Range	-65 to +150	°C
$P_D$	Power Dissipation	SOIC-14 TSSOP-14 1077 833	mW
$T_L$	Lead Temperature (Soldering 10 seconds)	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Unless otherwise specified all voltages are referenced to ground.

## RECOMMENDED OPERATING RANGES

Symbol	Parameter	Min.	Max.	Unit
$V_{CC}$	Supply Voltage	2	6	V
$V_{IN}, V_{OUT}$	Input Voltage	0	$V_{CC}$	V
$T_A$	Operating Temperature Range	-55	+125	°C
$t_r, t_f$	Input Rise or Fall Times $V_{CC} = 2.0$ V $V_{CC} = 4.5$ V $V_{CC} = 6.0$ V	- - -	1000 500 400	ns

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

# MM74HC164

## DC ELECTRICAL CHARACTERISTICS (Note 2)

Symbol	Parameter	V <sub>CC</sub> (V)	Test Conditions	T <sub>A</sub> = 25°C		T <sub>A</sub> = −40°C to 85°C	T <sub>A</sub> = −55°C to 125°C	Unit
				Typ.	Guaranteed Limits			
V <sub>IH</sub>	Minimum HIGH Level Input Voltage	2.0	–	–	1.5	1.5	1.5	V
		4.5		–	3.15	3.15	3.15	
		6.0		–	4.2	4.2	4.2	
V <sub>IL</sub>	Maximum LOW Level Input Voltage	2.0	–	–	0.5	0.5	0.5	V
		4.5		–	1.35	1.35	1.35	
		6.0		–	1.8	1.8	1.8	
V <sub>OH</sub>	Minimum HIGH Level Output Voltage	2.0	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> ,  I <sub>OUT</sub>   ≤ 20 μA	2.0	1.9	1.9	1.9	V
		4.5		4.5	4.4	4.4	4.4	
		6.0		6.0	5.9	5.9	5.9	
		4.5	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> ,  I <sub>OUT</sub>   ≤ 4.0 mA	4.2	3.98	3.84	3.7	
		6.0	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> ,  I <sub>OUT</sub>   ≤ 5.2 mA	5.7	5.48	5.34	5.2	
V <sub>OL</sub>	Maximum LOW Level Output Voltage	2.0	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> ,  I <sub>OUT</sub>   ≤ 20 μA	0	0.1	0.1	0.1	V
		4.5		0	0.1	0.1	0.1	
		6.0		0	0.1	0.1	0.1	
		4.5	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> ,  I <sub>OUT</sub>   ≤ 4.0 mA	0.2	0.26	0.33	0.4	
		6.0	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> ,  I <sub>OUT</sub>   ≤ 5.2 mA	0.2	0.26	0.33	0.4	
I <sub>IN</sub>	Maximum Input Current	6.0	V <sub>IN</sub> = V <sub>CC</sub> or GND	–	±0.1	±1.0	±1.0	μA
I <sub>CC</sub>	Maximum Quiescent Supply Current	6.0	V <sub>IN</sub> = V <sub>CC</sub> or GND, I <sub>OUT</sub> = 0 μA	–	8.0	80	160	μA

2. For a power supply of 5 V ±10% the worst case output voltages (V<sub>OH</sub>, and V<sub>OL</sub>) occur for HC at 4.5 V. Thus the 4.5 V values should be used when designing with this supply. Worst case V<sub>IH</sub> and V<sub>IL</sub> occur at V<sub>CC</sub> = 5.5 V and 4.5 V respectively. (The V<sub>IH</sub> value at 5.5 V is 3.85 V.) The worst case leakage current (I<sub>IN</sub>, I<sub>CC</sub>, and I<sub>OZ</sub>) occur for CMOS at the higher voltage and so the 6.0 V values should be used.

## AC ELECTRICAL CHARACTERISTICS (V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C, C<sub>L</sub> = 15 pF, t<sub>r</sub> = t<sub>f</sub> = 6 ns)

Symbol	Parameter	Typ.	Guaranteed Limit	Unit
f <sub>MAX</sub>	Maximum Operating Frequency	–	30	MHz
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay, Clock to Output	19	30	ns
t <sub>PHL</sub>	Maximum Propagation Delay, Clear to Output	23	35	ns
t <sub>REM</sub>	Minimum Removal Time, Clear to Clock	–2	0	ns
t <sub>S</sub>	Minimum Setup Time, Data to Clock	12	20	ns
t <sub>H</sub>	Minimum Hold Time, Clock to Data	1	5	ns
t <sub>W</sub>	Minimum Pulse Width, Clear or Clock	10	16	ns

# MM74HC164

## AC ELECTRICAL CHARACTERISTICS (C<sub>L</sub> = 50 pF, t<sub>r</sub> = t<sub>f</sub> = 6 ns unless otherwise specified)

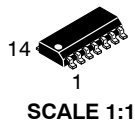
Symbol	Parameter	V <sub>CC</sub> (V)	Test Conditions	T <sub>A</sub> = 25°C		T <sub>A</sub> = −40°C to 85°C	T <sub>A</sub> = −55°C to 125°C	Unit
				Typ.	Guaranteed Limits			
f <sub>MAX</sub>	Maximum Operating Frequency	2.0		–	5	4	3	MHz
		4.5		–	27	21	18	
		6.0		–	31	24	20	
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay, Clock to Output	2.0	–	115	175	218	254	ns
		4.5		13	35	44	51	
		6.0		20	30	38	44	
t <sub>PHL</sub>	Maximum Propagation Delay, Clear to Output	2.0	–	140	205	256	297	ns
		4.5		28	41	51	59	
		6.0		24	35	44	51	
t <sub>REM</sub>	Minimum Removal Time, Clear to Clock	2.0	–	−7	0	0	0	ns
		4.5	–	−3	0	0	0	
		6.0	–	−2	0	0	0	
t <sub>S</sub>	Minimum Setup Time, Data to Clock	2.0	–	25	100	125	150	ns
		4.5		14	20	25	30	
		6.0		12	17	21	25	
t <sub>H</sub>	Minimum Hold Time, Clock to Data	2.0	–	−2	5	5	5	ns
		4.5		0	5	5	5	
		6.0		1	5	5	5	
t <sub>W</sub>	Minimum Pulse Width Clear or Clock	2.0	–	22	80	100	120	ns
		4.5		11	16	20	24	
		6.0		10	14	18	20	
t <sub>THL</sub> , t <sub>TLH</sub>	Maximum Output Rise and Fall Time	2.0	–	–	75	95	110	ns
		4.5		–	15	19	22	
		6.0		–	13	16	19	
t <sub>r</sub> , t <sub>f</sub>	Maximum Input Rise and Fall Time	2.0	–	–	1000	1000	1000	ns
		4.5		–	500	500	500	
		6.0		–	400	400	400	
C <sub>PD</sub>	Power Dissipation Capacitance (Note 4)	5.0	(per package)	150	–	–	–	pF
C <sub>IN</sub>	Maximum Input Capacitance	–		5	10	10	10	pF

3. C<sub>PD</sub> determines the no load dynamic power consumption, PD = C<sub>PD</sub> V<sub>CC</sub><sup>2</sup> f + I<sub>CC</sub> V<sub>CC</sub>, and the no load dynamic current consumption, I<sub>S</sub> = C<sub>PD</sub> V<sub>CC</sub> f + I<sub>CC</sub>.

## ORDERING INFORMATION

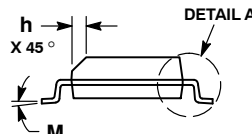
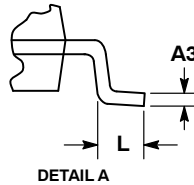
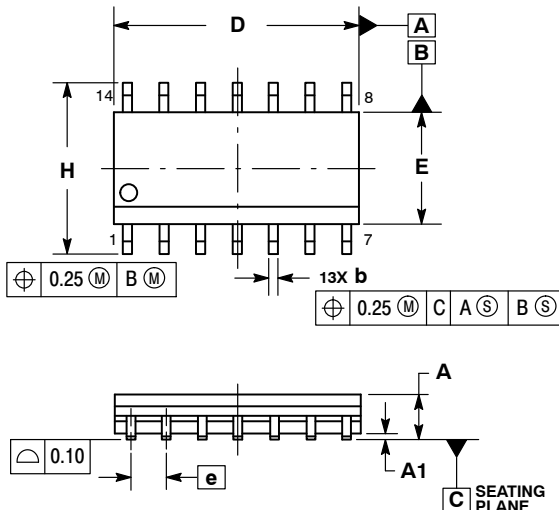
Product Number	Package	Shipping <sup>†</sup>
MM74HC164M	SOIC-14 NB (Pb-Free)	55 Units / Tube
MM74HC164MTCX	TSSOP-14 WB (Pb-Free)	2500 / Tape and Reel
MM74HC164MX	SOIC-14 (Pb-Free)	2500 / Tape and Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).



SOIC-14 NB  
CASE 751A-03  
ISSUE L

DATE 03 FEB 2016

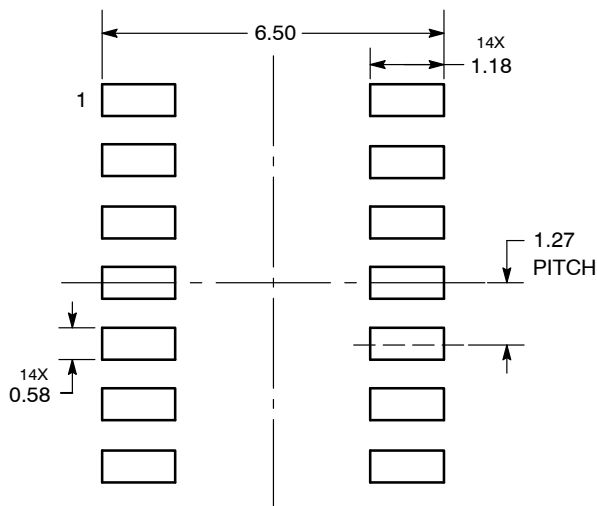


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
A3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0°	7°	0°	7°

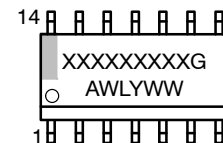
SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC  
MARKING DIAGRAM\*



XXXXXX = Specific Device Code  
A = Assembly Location  
WL = Wafer Lot  
Y = Year  
WW = Work Week  
G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

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SOIC-14  
CASE 751A-03  
ISSUE L

DATE 03 FEB 2016

STYLE 1:  
PIN 1. COMMON CATHODE  
2. ANODE/CATHODE  
3. ANODE/CATHODE  
4. NO CONNECTION  
5. ANODE/CATHODE  
6. NO CONNECTION  
7. ANODE/CATHODE  
8. ANODE/CATHODE  
9. ANODE/CATHODE  
10. NO CONNECTION  
11. ANODE/CATHODE  
12. ANODE/CATHODE  
13. NO CONNECTION  
14. COMMON ANODE

STYLE 2:  
CANCELLED

STYLE 3:  
PIN 1. NO CONNECTION  
2. ANODE  
3. ANODE  
4. NO CONNECTION  
5. ANODE  
6. NO CONNECTION  
7. ANODE  
8. ANODE  
9. ANODE  
10. NO CONNECTION  
11. ANODE  
12. ANODE  
13. NO CONNECTION  
14. COMMON CATHODE

STYLE 4:  
PIN 1. NO CONNECTION  
2. CATHODE  
3. CATHODE  
4. NO CONNECTION  
5. CATHODE  
6. NO CONNECTION  
7. CATHODE  
8. CATHODE  
9. CATHODE  
10. NO CONNECTION  
11. CATHODE  
12. CATHODE  
13. NO CONNECTION  
14. COMMON ANODE

STYLE 5:  
PIN 1. COMMON CATHODE  
2. ANODE/CATHODE  
3. ANODE/CATHODE  
4. ANODE/CATHODE  
5. ANODE/CATHODE  
6. NO CONNECTION  
7. COMMON ANODE  
8. COMMON CATHODE  
9. ANODE/CATHODE  
10. ANODE/CATHODE  
11. ANODE/CATHODE  
12. ANODE/CATHODE  
13. NO CONNECTION  
14. COMMON ANODE

STYLE 6:  
PIN 1. CATHODE  
2. CATHODE  
3. CATHODE  
4. CATHODE  
5. CATHODE  
6. CATHODE  
7. CATHODE  
8. ANODE  
9. ANODE  
10. ANODE  
11. ANODE  
12. ANODE  
13. ANODE  
14. ANODE

STYLE 7:  
PIN 1. ANODE/CATHODE  
2. COMMON ANODE  
3. COMMON CATHODE  
4. ANODE/CATHODE  
5. ANODE/CATHODE  
6. ANODE/CATHODE  
7. ANODE/CATHODE  
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12. COMMON ANODE  
13. ANODE/CATHODE  
14. ANODE/CATHODE

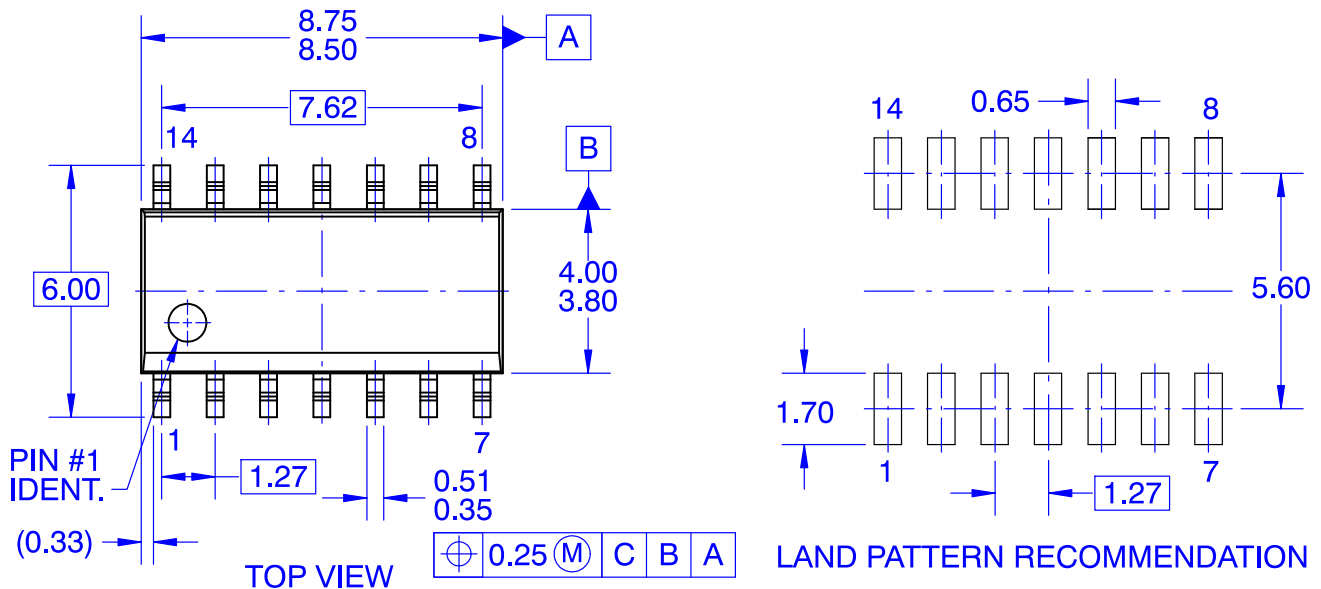
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PIN 1. COMMON CATHODE  
2. ANODE/CATHODE  
3. ANODE/CATHODE  
4. NO CONNECTION  
5. ANODE/CATHODE  
6. ANODE/CATHODE  
7. COMMON ANODE  
8. COMMON ANODE  
9. ANODE/CATHODE  
10. ANODE/CATHODE  
11. NO CONNECTION  
12. ANODE/CATHODE  
13. ANODE/CATHODE  
14. COMMON CATHODE

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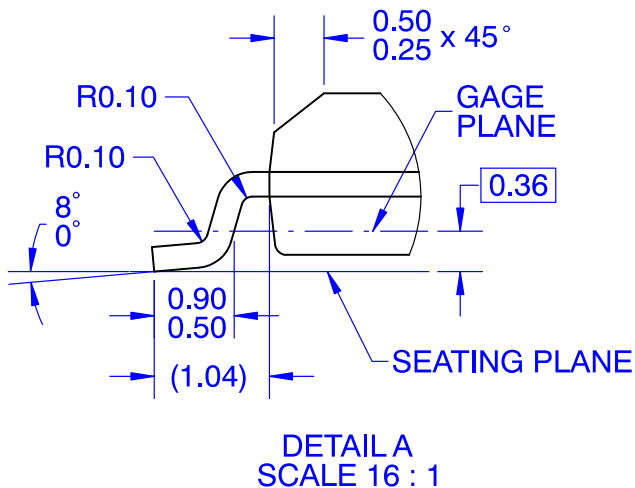
**SOIC14**  
**CASE 751EF**  
**ISSUE O**

DATE 30 SEP 2016



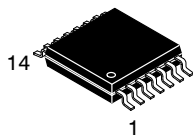
**NOTES:**

- A. CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C
- B. ALL DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS
- D. LAND PATTERN STANDARD: SOIC127P600X145-14M
- E. CONFORMS TO ASME Y14.5M, 2009



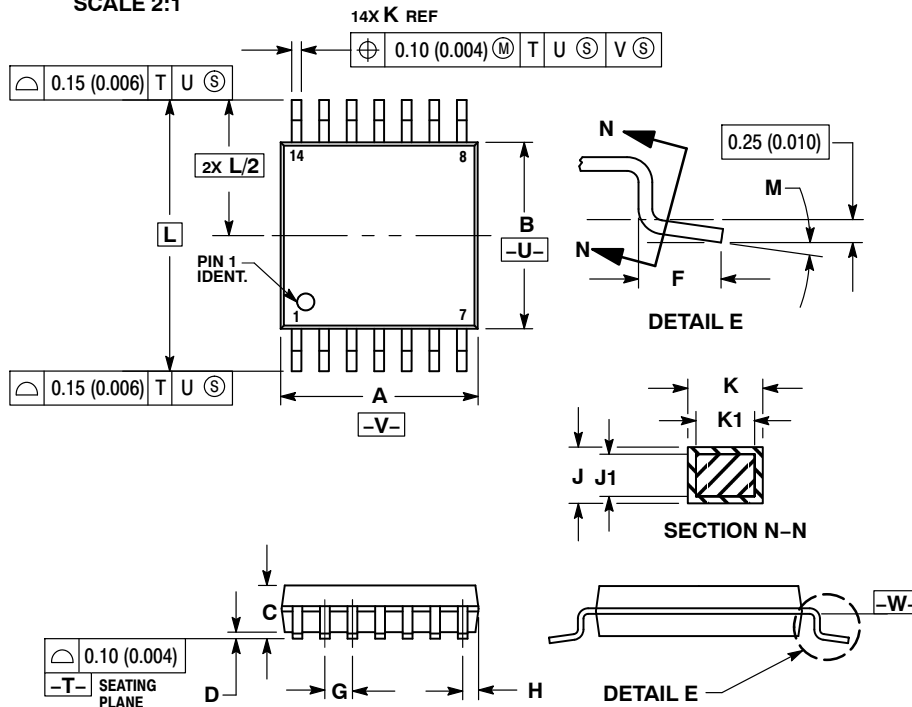
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**TSSOP-14 WB**  
CASE 948G  
ISSUE C

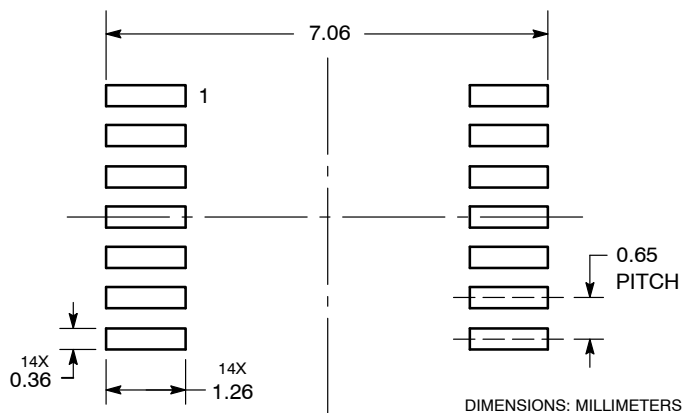
DATE 17 FEB 2016

SCALE 2:1

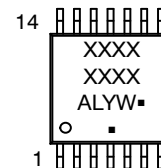

**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

**RECOMMENDED  
SOLDERING FOOTPRINT\***


\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**GENERIC  
MARKING DIAGRAM\***


A = Assembly Location  
L = Wafer Lot  
Y = Year  
W = Work Week  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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**DESCRIPTION:** TSSOP-14 WB

**PAGE 1 OF 1**

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